

Automotive Process Change Notification

Date: December 12, 2013

PCN Reference: AU-13-32A, Qualification of Vanguard International Semiconductor Corporation (VIS) for Gen10.2 MOSFET Technology

Product Reference: Gen10.2 MOSFET (Logic Level)

To Our Valued Customer:

We thank you for your use of International Rectifier (IR) semiconductor products. Our commitment to customer satisfaction and continuous improvement is demonstrated by our change plans to enhance capacity, quality and reliability. We would like to express our sincere appreciation for your cooperation regarding the following changes, and IR will work closely with you to support your requirements during this transition.

Type of Change Notification:

- Wafer fab site
- Test site

Description of Change:

Gen10.2 MOSFET products currently manufactured and wafer-level tested in the IR Newport, South Wales UK (Fab 11) eight inch facility will be transferred to the VIS Hsinchu, Taiwan (Fab 2) eight inch wafer fab and subcontractor facilities.

Reason for the Change:

As part of a manufacturing consolidation plan announced in 2012, International Rectifier indicated that it would be closing the IR Fab 10 facility and transferring the production capability for certain parts to foundries. In order to enable capacity expansion, other Gen10.2 technology parts from the IR Fab 11 facility will also be transferred to VIS.

Effective Date:

June 12, 2014

Products Affected:

AUIRL1404Z	TO-220	AUIRLR3705ZTR	D-Pak
AUIRL1404ZL	D ² Pak	AUIRLR3705ZTRR	D-Pak
AUIRL1404ZS	D ² Pak	AUIRLZ44Z	TO-220
AUIRL1404ZSTRL	D ² Pak	AUIRLZ44ZL	D ² Pak
AUIRL3705Z	TO-220	AUIRLZ44ZS	D ² Pak
AUIRL3705ZL	D ² Pak	AUIRLR024Z	D-Pak
AUIRL3705ZS	D ² Pak	AUIRLU024Z	I-Pak
AUIRL3705ZSTRL	D ² Pak	AUIRLL024Z	SOT-223
AUIRLR2905Z	D-Pak		
AUIRLR2905ZTR	D-Pak		
AUIRLR2905ZTRL	D-Pak		
AUIRLR3705Z	D-Pak		

Impact of Change:

No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of materials and the location for assembly and final test will not change.

Method of Identifying Changed Product:

Wafer fab origins will not be distinguished through the external part making or shipping labels; however, based on the assembly lot code marked on the device, IR internal systems will be able to trace the site of the wafer lots used to produce the final product.

Qualification and Supporting Data Availability:

Available now.

Sample Availability:

Available now.

Contact Information:

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